



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE92464ED	Issued	08. April 2022
MA#	MA005563509		
Package	PG-DSO-36-72	Weight*	539.31 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.051	1.12	1.12	11220	11220
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		134	
	non noble metal	iron	7439-89-6	0.241	0.04		447	
	non noble metal	copper	7440-50-8	240.973	44.68	44.73	446817	447398
wire	non noble metal	copper	7440-50-8	3.150	0.58	0.58	5841	5841
encapsulation	organic material	carbon black	1333-86-4	0.830	0.15		1540	
	plastics	epoxy resin	-	32.385	6.00		60048	
	inorganic material	silicondioxide	60676-86-0	243.576	45.19	51.34	451643	513231
leadfinish	non noble metal	tin	7440-31-5	6.656	1.23	1.23	12341	12341
plating	noble metal	silver	7440-22-4	3.599	0.67	0.67	6673	6673
glue	plastics	epoxy resin	-	0.311	0.06		577	
	noble metal	silver	7440-22-4	1.467	0.27	0.33	2719	3296
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com